

Product Change Notification / RMES-24DZDY117

Date:

28-Jul-2020

Product Category:

Ethernet Switches

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3847 Final Notice: Qualification of GTK as a new assembly site for selected KSZ8852xx Micrel device family available in 64L LQFP (10x10x1.4mm) package.

Affected CPNs:

RMES-24DZDY117_Affected_CPN_07282020.pdf RMES-24DZDY117_Affected_CPN_07282020.csv

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of GTK as a new assembly site for selected KSZ8852xx Micrel device family available in 64L LQFP (10x10x1.4mm) package.

Pre Change:

Assembled at TICP using CEL-9200 mold compound material

Post Change:

Assembled at GTK using G700H mold compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp (TICP)	GREATEK ELETRONIC INC. (GTK)
Wire material	Au	Au
Die attach material	EN4900	EN4900
Molding compound material	CEL-9200	G700H
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTK as a new assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

August 28, 2020 (date code: 2035)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

	June 2019					>	July 2020					August 2020					
Workweek	22	23	24	25	26		27	28	29	30	31	32	33	34	35	36	
Initial PCN Issue					Х												
Date					^												
Qual Report											Х						

Availability	I								
Final PCN Issue						v			
Date						~			
Estimated									
Implementation								Х	
Date									

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

June 26, 2019: Issued initial notification. July 28, 2020: Issued final notification. Attached is the qualification report and added estimated first ship date by August 28, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_RMES-24DZDY117_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. RMES-24DZDY117 - CCB 3847 Final Notice: Qualification of GTK as a new assembly site for selected KSZ8852xx Micrel device family available in 64L LQFP (10x10x1.4mm) package.

Affected Catalog Part Numbers (CPN)

KSZ8852HLEWA KSZ8852HLEYA